

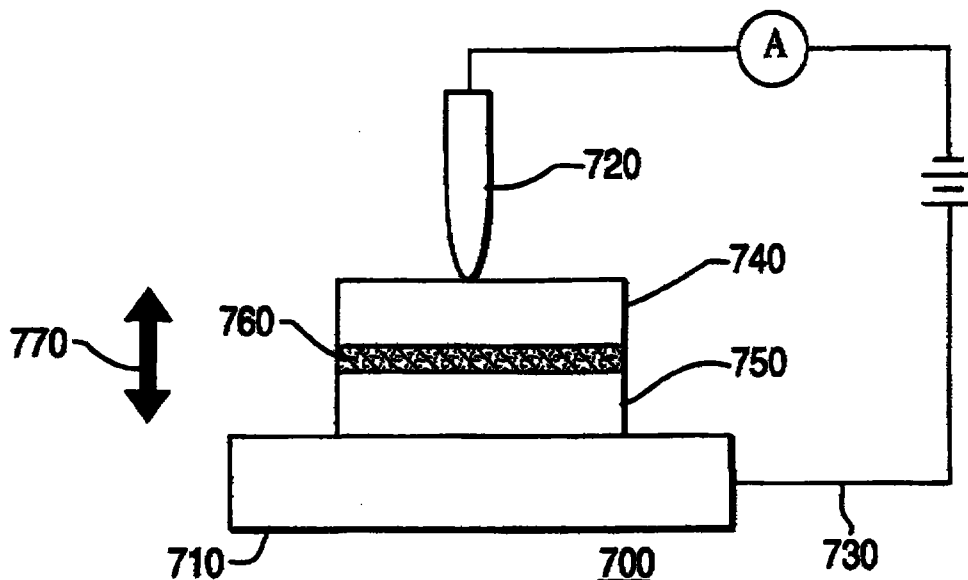


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(21) International Application Number: PCT/US95/14654 (22) International Filing Date: 9 November 1995 (09.11.95) (71) Applicant: DAVID SARNOFF RESEARCH CENTER, INC. [US/US]; 201 Washington Road, CN5300, Princeton, NJ 08543-5300 (US). (72) Inventors: FAN, Zhong-Hui; 32-09 Ravens Crest Drive, Plainsboro, NJ 08536 (US). CHERUKURI, Satyam, C.; 90 Cranbury Road, Cranbury, NJ 08512 (US). LEVINE, Aaron, W.; 6 Springwood Drive, Lawrenceville, NJ 08648 (US). LIPP, Steven, A.; 9 Woodland Court, Cranbury, NJ 08512 (US). (74) Agent: BURKE, William, J.; David Sarnoff Research Center, Inc., 201 Washington Road CN5300, Princeton, NJ 08543-5300 (US).	(81) Designated States: AM, AU, BB, BG, BR, BY, CA, CN, CZ, EE, FI, GE, HU, IS, JP, KG, KP, KR, KZ, LK, LR, LT, LV, MD, MG, MN, MX, NO, NZ, PL, RO, RU, SG, SI, SK, TJ, TM, TT, UA, UZ, VN, ARIPO patent (KE, LS, MW, SD, SZ, UG), European patent (AT, BE, CH, DE, DK, ES, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>	

(54) Title: FIELD-ASSISTED SEALING**(57) Abstract**

The invention provides a method of bonding a glass substrate (740) and a nonconductive substrate (750) comprising the steps of: (a) contacting a surface of the nonconductive substrate (750), which is coated with a field-assist bonding material (760), with a conforming surface of the glass substrate (740); and (b) applying sufficient heat to the two substrates and sufficient voltage across the two substrates to bond the two substrates together.